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PPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/063,975	05/30/2002	Chih-Jung Ni	8642-US-PA	4063
31561	7590 06/09/20	04	EXAMINER	
•	YUN INTELLECT	VINH, LAN		
7 FLOOR-1, NO. 100 ROOSEVELT ROAD, SECTION 2			ART UNIT	PAPER NUMBER
	00	_	1765	
TAIWAN			DATE MAILED: 06/09/200	4

Please find below and/or attached an Office communication concerning this application or proceeding.

. •	Application No.	Applicant(s)	
	10/063,975	NI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Lan Vinh	1765	
The MAILING DATE of this communication Period for Reply	on appears on the cover sheet w		s
A SHORTENED STATUTORY PERIOD FOR F THE MAILING DATE OF THIS COMMUNICAT - Extensions of time may be available under the provisions of 37 (after SIX (6) MONTHS from the mailing date of this communicat - If the period for reply specified above, the maximum statutory - Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ION. CFR 1.136(a). In no event, however, may a lion. s, a reply within the statutory minimum of thin period will apply and will expire SIX (6) MON a statute, cause the application to become A	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this community of the community	ication.
Status			
1)⊠ Responsive to communication(s) filed on	30 May 2003		
	This action is non-final.		•
3) Since this application is in condition for a		ers prosecution as to the mor	ite ie
closed in accordance with the practice un			113 13
Disposition of Claims	,,		•
4) ☐ Claim(s) <u>1-9</u> is/are pending in the applica	tion		
4a) Of the above claim(s) is/are with	•		
5) Claim(s) <u>1,2,8 and 9</u> is/are allowed.	indrawn from consideration.		
6)⊠ Claim(s) <u>7-2,0 and 9</u> is/are allowed.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction a	and/or cloation requirement		
	and/or election requirement.		
Application Papers			
9) The specification is objected to by the Exa			
10)⊠ The drawing(s) filed on <u>30 May 2003</u> is/ard			
Applicant may not request that any objection t			
Replacement drawing sheet(s) including the c			
11)☐ The oath or declaration is objected to by the	ne Examiner. Note the attached	Office Action or form PTO-15	2.
Priority under 35 U.S.C. § 119			
12)⊠ Acknowledgment is made of a claim for fo a)⊠ All b)□ Some * c)□ None of:	reign priority under 35 U.S.C. §	119(a)-(d) or (f).	
1. Certified copies of the priority docur	ments have been received		
2. Certified copies of the priority docur		oplication No. 10/063 975	
3. Copies of the certified copies of the			,
application from the International Bu		received in the Haderial Otage	^
* See the attached detailed Office action for a	• • • • • • • • • • • • • • • • • • • •	eceived.	
Attachment(e)			
Attachment(s) 1) Notice of References Cited (PTO-892)	🗖		
2) Notice of Praftsperson's Patent Drawing Review (PTO-94)	4) ∐ Interview Si 8) Paper No(s	ummary (PTO-413))/Mail Date	
3) Information Disclosure Statement(s) (PTO-1449 or PTO/S	B/08) 5) Notice of In	formal Patent Application (PTO-152)	
Paper No(s)/Mail Date S. Patent and Trademark Office	6)	_•	
	ice Action Summary	Part of Paper No./Mail Date 0	60204

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claim 3 is rejected under 35 U.S.C. 102(b) as being anticipated by Fukazawa et al (US 5,810,940)

Fukazawa discloses a method for cleaning semiconductor wafer in a cleaning vessel/reactor using a controller to control a concentration of the mixed acid solution (col 5, lines 20-30), the concentration of the mixed solution being controlled by providing a time period list including time interval and added amount of HF (claimed spiking amount of a third acid) (col 5, lines 30-35, fig. 2B), fig. 2B also shows the added amounts of HF are constant, which reads on the spiking amounts are constant. The added amounts of HF/spiking amount of third acid is also seen being introduced into the vessel/reactor based on the time interval setting as seen in fig. 2B

3. Claims 4-5 are rejected under 35 U.S.C. 102(b) as being anticipated by Verhaverbeke et al (US 6,132,522)

Verhaverbeke discloses a wet processing method using a processing system having a vessel to control a concentration of reactive process fluid containing acid (col 6, lines 40-46; col 10, lines 60-65), the concentration of the reactive process fluid being

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controlled by providing a list of a plurality of run number of wafer and a plurality of spiking amount of HF/first acid liquid corresponding to run numbers of wafer (col 7, lines 55-60; col 10, lines 38-40, Table 3), which reads on providing a charge list including a plurality of lot numbers of product and a plurality of spiking amount of a first acid liquid corresponding to lot numbers of product

displacing the SC1 chemical mixture by HF in an order corresponding to the run number of wafer (col 14, lines 40-45, Table 3), which reads on introducing the spiking amounts of the first acid into the reactor in an order corresponding to the lot numbers of product

Regarding claim 5, Verhaverbeke discloses that HF can be used in a cleaning step after an etching step (col 9, lines 35-42), which reads on the acid liquid is not introduced into the reactor when a wafer is being etched

4. Claims 6-7 are rejected under 35 U.S.C. 102(b) as being anticipated by Fukazawa et al (US 5,810,940)

Fukazawa discloses a method for cleaning semiconductor wafer in a cleaning vessel/reactor using a controller to control a concentration of the mixed acid solution (col 5, lines 20-30), the concentration of the mixed solution being controlled by providing a time period list including timing points (T12 and T13) during which HF is added/spike timing points and added amount of HF (claimed second acid) (col 5, lines 30-35, fig. 2B). The added amounts of HF/spiking amount of second acid is also seen being introduced into the vessel/reactor based on the timing points as seen in fig. 2B

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Regarding claim 7, Fukazawa discloses using HF as a cleaning fluid (col 3, lines 47-49), which reads on the acid liquid is not introduced into the reactor when a wafer is being etched

Allowable Subject Matter

5. Claims 1-2, 8-9 allowed.

The following is an examiner's statement of reasons for allowance:

Regarding claims 1, 8, the prior art of record fails to disclose or render obvious a method for spiking a mixed acid liquid in a reactor by using a computer to control a concentration of the mixed acid liquid, the concentration of the mixed acid liquid being controlled at a based-on-time-and-charge mode comprising introducing the spiking amounts of the first acid into the reactor based on the lot number of products and the spike timing point, in combination with the rest of the limitations of claims 1 and 8.

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Conclusion

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lan Vinh whose telephone number is 571 272 1471. The examiner can normally be reached on M-F 8:30-5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571 272 1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

LV

June 3, 2004